

40V N-Channel Enhancement Mode MOSFET

Voltage 40 V Current 140 A

Features

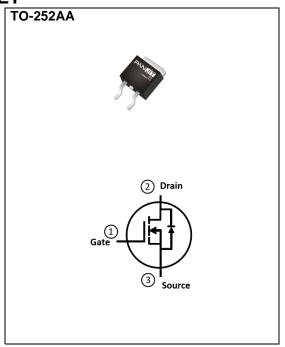
- RDS(ON), VGS@10V, ID@20A<3.3m Ω
- RDS(ON), VGS@4.5V, ID@20A<4.3m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: TO-252AA Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.3217 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C	l _D	140		
	T _C =100°C		99	Α	
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	560		
Power Dissipation	T _C =25°C	Po	115	W	
	T _C =100°C		58		
Continuous Drain Current(Note 4)	T _A =25°C	Ι _D	22.5	Λ	
	T _A =70°C		18.8	A	
Power Dissipation	T _A =25°C	D-	3	W	
	T _A =70°C	Pb	2.1		
Single Pulse Avalanche Energy ^(Note 5)		Eas	114	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{0JC}	1.3	°C/W	
	Junction to Ambient	$R_{\theta JA}$	50		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	40	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	1.1	1.6	2.3	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	2.6	3.3	mΩ
		V _{GS} =4.5V, I _D =20A	-	3.3	4.3	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	±1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Qg	V _{DS} =32V, I _D =20A, V _{GS} =10V	-	41	-	nC
Gate-Source Charge	Qgs		-	7	-	
Gate-Drain Charge	Q_{gd}		-	5	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHz	-	2862	-	pF
Output Capacitance	Coss		-	560	-	
Reverse Transfer Capacitance	Crss		-	58	-	
Gate resistance	Rg	f=1MHz	-	1	-	Ω
Turn-On Delay Time	td _(on)	V _{DS} =32V, I _D =20A, V _{GS} =10V, R _G =3Ω (Note 2)	-	15	-	ns
Turn-On Rise Time	tr		-	5	-	
Turn-Off Delay Time	td _(off)		-	46	-	
Turn-Off Fall Time	tf	(11010 2)	-	10	-	
Drain-Source Diode						
Diode Forward Current	Is	T 05°0	-	-	140	А
Pulsed Diode Forward Current	I _{SM}	T _C =25°C	-	-	560	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.8	1.3	V
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A dI _S /dt=100A/us	-	38	-	ns
Reverse Recovery Charge	Qrr		-	35	-	nC

NOTES:

- 1. Pulse width<a>100us, Duty cycle<a>2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an ReJC=1.3°C/W, Package limited 100A.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS} =21A, V_{DD} =30V, V_{GS} =10V, Starting T_{J} =25°C. the chip is about to carry I_{AS} =43A.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

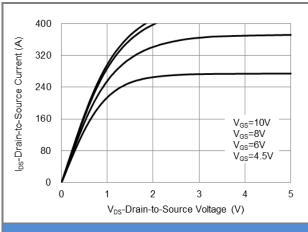


Fig.1 On-Region Characteristics

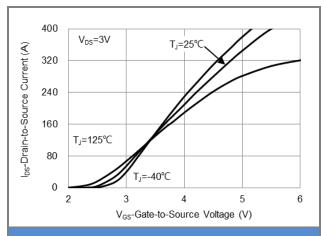


Fig.2 Transfer Characteristics

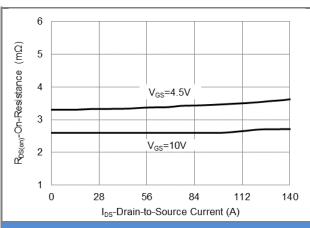


Fig.3 On-Resistance vs. Drain Current

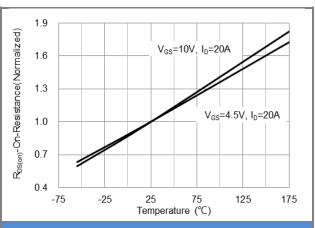
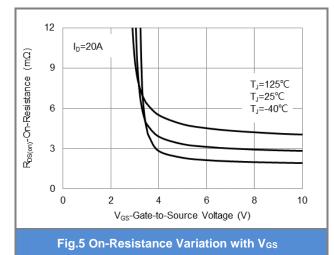
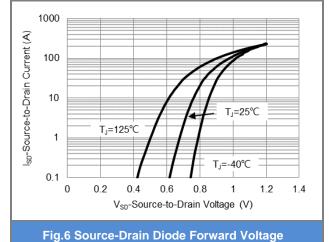


Fig.4 On-Resistance vs. Junction temperature





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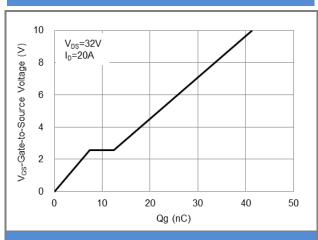


Fig.7 Gate-Charge Characteristics

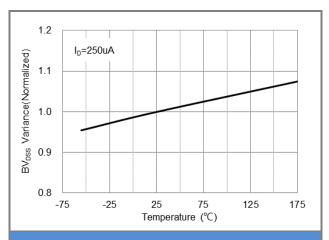


Fig.8 Breakdown Voltage Variation vs. Temperature

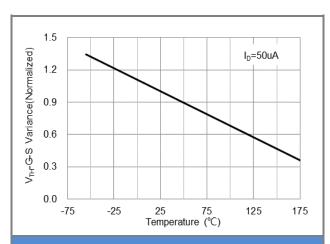


Fig.9 Threshold Voltage Variation with Temperature

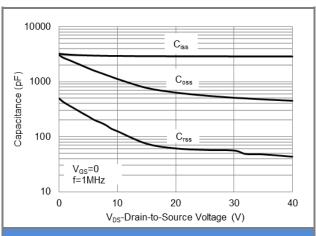
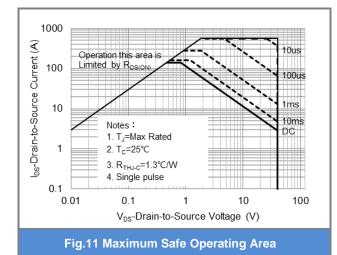


Fig.10 Capacitance vs. Drain-Source Voltage



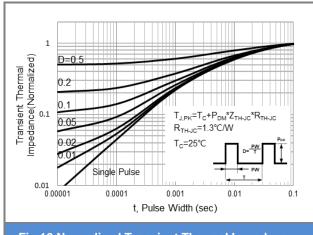


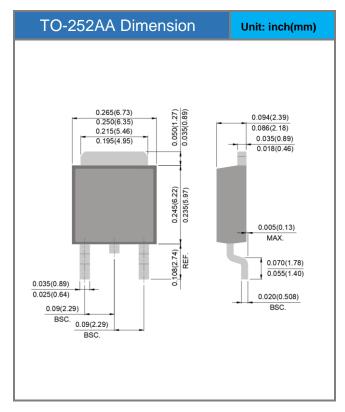
Fig.12 Normalized Transient Thermal Impedance

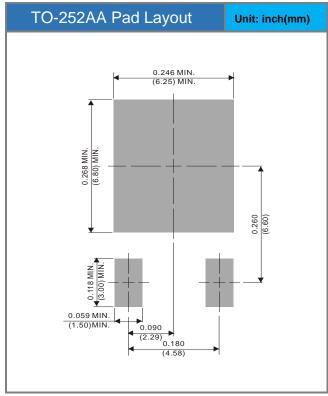


Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PJD60N04S-AU	TO-252AA	3K pcs / 13" reel	D60N04S

Packaging Information & Mounting Pad Layout







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